2SB0792, 2SB0792A (2SB792, 2SB792A)

Silicon PNP epitaxial planer type

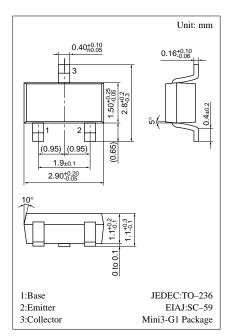
For high breakdown voltage low-noise amplification Complementary to 2SD0814 (2SD814)

Features

- High collector to emitter voltage V_{CEO}.
- Low noise voltage NV.
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

		•			
Parameter		Symbol	Ratings	Unit	
Collector to	2SB0792	17	-150	V	
base voltage	2SB0792A	V _{CBO}	-185	V	
Collector to	2SB0792	V	-150	v	
emitter voltage	2SB0792A	V _{CEO}	-185	v	
Emitter to base voltage		V_{EBO}	-5	V	
Peak collector current		I _{CP}	-100	mA	
Collector current		I _C	-50	mA	
Collector power dissipation		P _C	200	mW	
Junction temperature		Tj	150	°C	
Storage temperature		T _{stg}	-55 ~ +150	°C	

Absolute Maximum Ratings (Ta=25°C)



 $\begin{array}{l} \mbox{Marking symbol}: I(2SB0792) \\ 2F(2SB0792A) \end{array}$

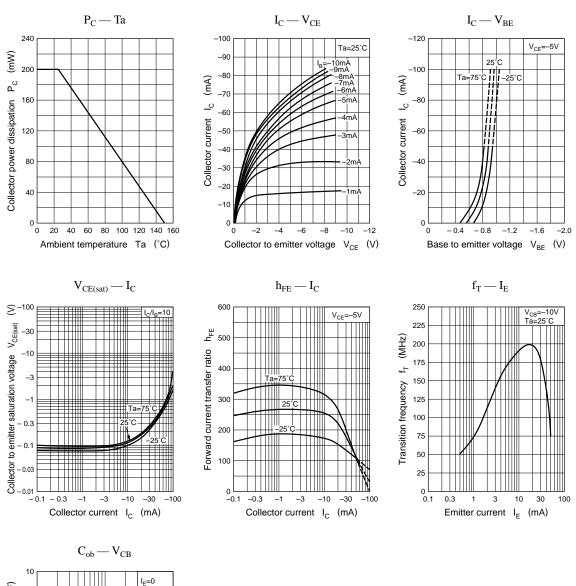
Electrical Characteristics (Ta=25°C)

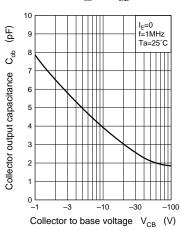
Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff current		I _{CBO}	$V_{CB} = -100V, I_E = 0$			-1	μΑ
Collector to emitter	2SB0792	17	I 100 A I 0	-150			v
voltage	2SB0792A	V _{CEO}	$I_{C} = -100 \mu A, I_{B} = 0$	-185			
Emitter to base voltage		V _{EBO}	$I_{\rm E} = -10 \mu A, \ I_{\rm C} = 0$	-5			V
Forward current	2SB0792			130		450	
transfer ratio	2SB0792A	h _{FE} *	$V_{CE} = -5V, I_C = -10mA$	130		330	
Collector to emitter saturation voltage		V _{CE(sat)}	$I_{C} = -30\mu A, I_{B} = -3mA$			-1	V
Transition frequency		f _T	$V_{CB} = -10V$, $I_E = 10mA$, $f = 200MHz$		200		MHz
Collector output capacitance		C _{ob}	$V_{CB} = -10V, I_E = 0, f = 1MHz$		4		pF
Noise voltage		NV	$V_{CE} = -10V, I_{C} = -1mA, G_{V} = 80dB,$ $R_{g} = 100k\Omega, Function = FLAT$		150		mV

*hFE Rank classification

Rank		R	S	Т	
h _{FE}		130 ~ 220	185 ~ 330	260 ~ 450	
Marking	2SB0792	IR	IS	IT	
Symbol	2SB0792A	2FR	2FS	_	

Note.) The Part numbers in the Parenthesis show conventional part number.





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